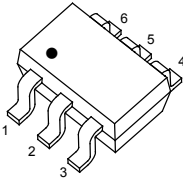
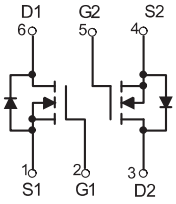
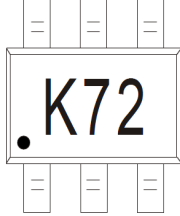


Dual N-channel MOSFET	SOT-363 Plastic-Encapsulate MOSFETs
<p style="text-align: center;"><u>SOT-363</u></p>  <p style="text-align: center;"><b>Equivalent Circuit</b></p> 	<p><b>Features</b></p> <ul style="list-style-type: none"> <li>High density cell design for low <math>R_{DS(ON)}</math></li> <li>Voltage controlled small signal switch</li> <li>Rugged and reliable</li> <li>High saturation current capability</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>Load Switch for Portable Devices</li> <li>DC/DC Converter</li> </ul> <p style="text-align: center;"><b>MARKING</b></p> 

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
60V	$5\Omega@10V$	115mA
	$7\Omega@5V$	

**MAXIMUM RATINGS ( $T_a=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-Source voltage	60	V
$V_{GS}$	Gate-Source voltage	$\pm 20$	V
$I_D$	Drain Current	115	mA
$P_D$	Power Dissipation	150	mW
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	833	$^\circ C/W$
$T_J$	Junction Temperature	150	$^\circ C$
$T_{stg}$	Storage Temperature	-55-150	$^\circ C$

### MOSFET ELECTRICAL CHARACTERISTICS

T<sub>a</sub>=25 °C unless otherwise specified

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250 μA	60			V
Gate-threshold voltage *	V <sub>th(GS)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	1	1.6	2.5	
Gate-body leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0 V, V <sub>GS</sub> =±20 V			±80	nA
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =60 V, V <sub>GS</sub> =0 V			80	nA
Drain-source on-resistance *	R <sub>DS(on)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =500mA		1.1	5	Ω
		V <sub>GS</sub> =5 V, I <sub>D</sub> =50mA		1.2	7	
Forward transconductance *	g <sub>fs</sub>	V <sub>DS</sub> =10 V, I <sub>D</sub> =200mA	80			ms
Drain-source on-voltage *	V <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =500mA			3.75	V
		V <sub>GS</sub> =5V, I <sub>D</sub> =50mA			0.375	V
Diode forward voltage	V <sub>SD</sub>	I <sub>S</sub> =115mA, V <sub>GS</sub> =0 V	0.55		1.2	V
Input capacitance **	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz			50	pF
Output capacitance **	C <sub>oss</sub>				25	
Reverse transfer capacitance **	C <sub>rss</sub>				5	

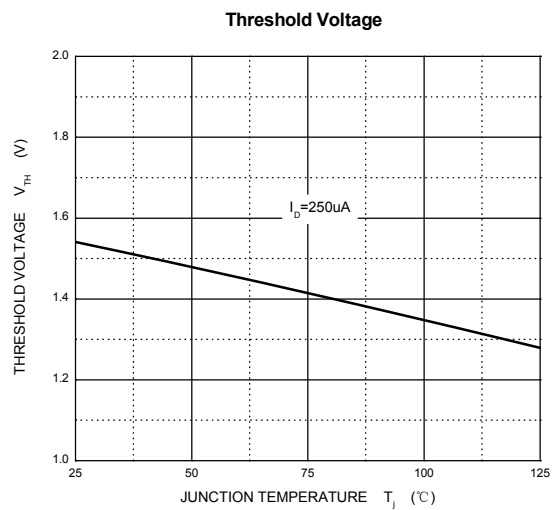
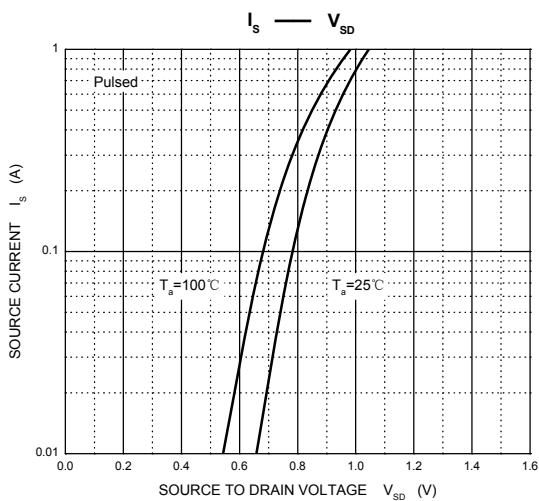
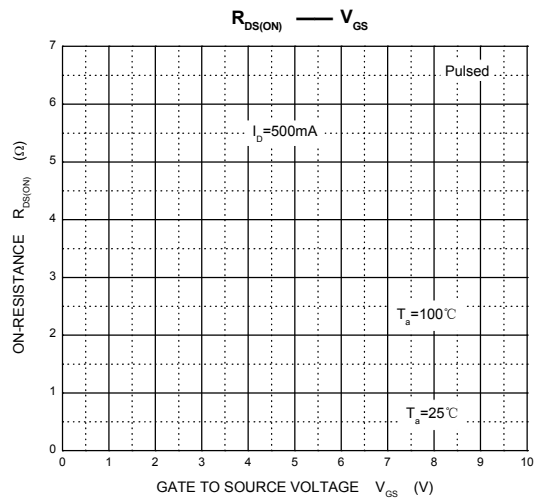
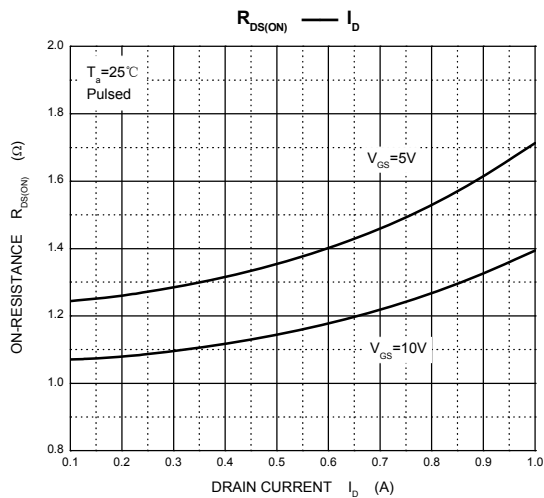
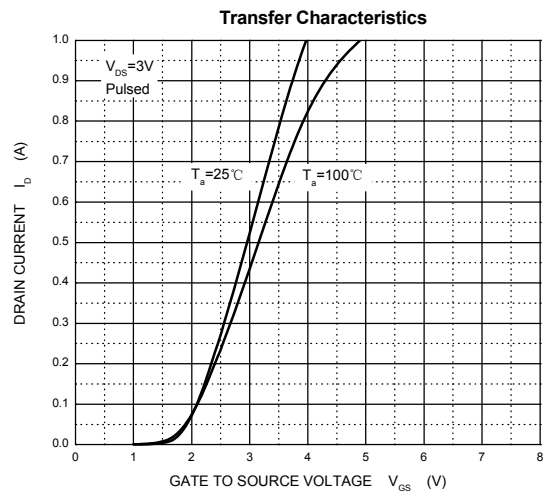
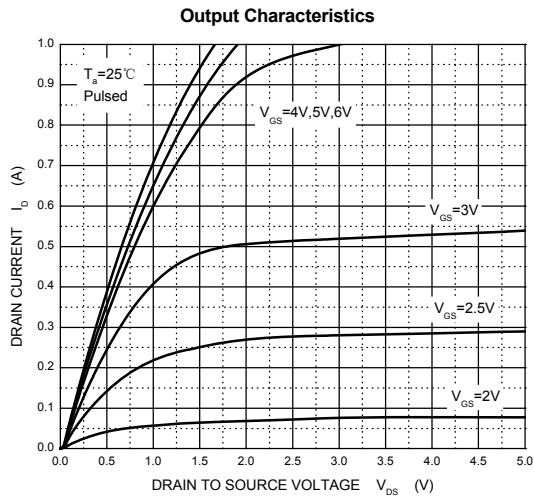
#### SWITCHING TIME

Turn-on time **	t <sub>d(on)</sub>	V <sub>DD</sub> =25 V, R <sub>L</sub> =50Ω			20	ns
Turn-off time **	t <sub>d(off)</sub>	I <sub>D</sub> =500mA, V <sub>GEN</sub> =10V, G=25 Ω			40	

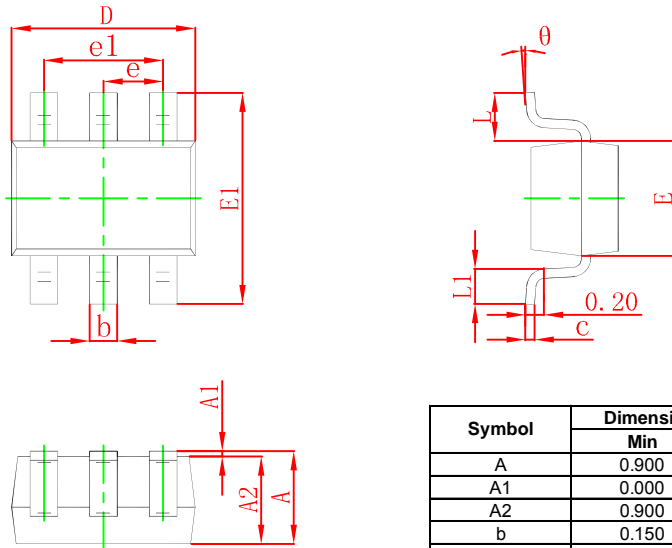
\* Pulse Test: Pulse width ≤300μs, duty cycle≤2%.

\*\* These parameters have no way to verify.

**Typical Characteristics**

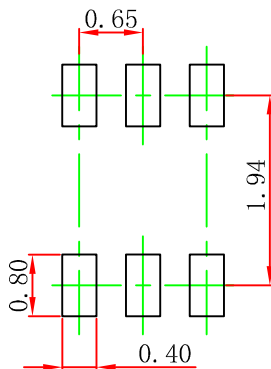


### SOT-363 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
theta	0°	8°	0°	8°

### SOT-363 Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05$  mm.
  3. The pad layout is for reference purposes only.

单击下面可查看定价，库存，交付和生命周期等信息

[>>DIOS\(迪恩思\)](#)